

6. (Amended) A substrate for mounting an electronic part or parts thereon comprising a core substrate and at least a set of insulation layer and a patterned wiring line layer which is formed on the insulation layer, said set of insulation layer and patterned wiring line layer being positioned at at least one of two opposed sides of the core substrate, the core substrate having holes, in each of which a lead pin of the electronic part is to be inserted, and said core substrate being provided with lands which surround an opening of each of the holes and to which the lead pin inserted in the hole is to be bonded, wherein the insulation layer or insulation layers located at at least one side of the core substrate has bores having a diameter larger than the diameter of the holes so as to expose the land and communicate with the hole surrounded by the land, at the bottom of the bores;

wherein the holes, in which the lead pin of the electronic part is to be inserted, have a closed end at the side of the core substrate opposed to the side on which the electronic parts are to be mounted.

7. (Amended) A substrate for mounting an electronic part or parts thereon comprising a core substrate and at least a set of insulation layer and a patterned wiring line layer which is formed on the insulation layer, said set of insulation layer and patterned wiring line layer being positioned at at least one of two opposed sides of the core substrate, the core substrate having holes, in each of which a lead pin of the electronic part is to be inserted, and said core substrate being provided with lands which surround an opening of each of the holes and to which the lead pin inserted in the hole is to be bonded, wherein the insulation layer or insulation layers located at at least one side of the core substrate has bores having a diameter larger than the diameter of the holes so as to expose the land and communicate with the hole surrounded by the land, at the bottom of the bores;

wherein at least one of the holes, in which the lead pin of the electronic part is to be inserted, has an open end at the side of the core substrate opposed to the side on which the electronic parts are to be mounted, and at least one of the holes, in which the lead pin of the electronic part is to be inserted, has a closed end at the side of the core substrate opposed to the side on which the electronic parts are to be mounted.

13. (Amended) A method of manufacturing a substrate for mounting an electronic part or parts thereon, comprising a core substrate and at least a set of insulation layer and patterned wiring line layer, which is formed on the insulation layer, at at least one sides of the core substrate, the core substrate having holes, in each of which a lead pin of the electronic part to be mounted is to be inserted, and being provided with lands which surround the opening of the hole and to which the lead pin inserted in the hole is to be bonded, and holes having an inside wall on which a conductor layer is formed, the conductor layer extending to a land provided on each of the sides of the core substrate in order to connect a wiring line at one side of the core substrate to another wiring line at the opposed side, the land surrounding the opening of the hole in which a lead pin of the electronic part is to be inserted, wherein the insulation layer or layers have bores having a diameter larger than the diameter of the holes so as to expose the land and communicate with the holes, at a bottom of the bores, and the lands connected to the wiring lines are covered with the insulation layer,

the method comprising the following steps:

providing a core substrate,

forming holes piercing the core substrate,

forming, on the core substrate and around the ends of the holes, lands for the connection with the lead pin of the electronic parts to be mounted, and lands for the connection with the wiring line layers,

filling the holes with a filling material,
forming at least a set of insulation layer and patterned wiring line layer, which is
formed on the insulation layer, at at least one side of the core substrate,
forming bores piercing through the resultant insulation layer or layers at the side of
the core substrate on which the electronic part or parts are to be mounted, and exposing the
land at the bottom of the bores, and
removing the filling material in the holes, in which a lead pin of the electronic part
is to be inserted, to allow each of the holes to communicate with each of the bores.

20. (Amended) A substrate for mounting an electronic part or parts thereon,
comprising a core substrate and at least a set of insulation layer and patterned wiring line
layer, which is formed on the insulation layer, at opposed sides of the core substrate, the
core substrate having holes, in each of which a lead pin of the electronic part to be mounted
is to be inserted, and being provided with lands which surround an opening of the hole and
to which the lead pin inserted in the hole is to be bonded, and holes having an inside wall
on which a conductor layer is formed, the conductor layer extending to a land provided on
each of the sides of the core substrate in order to connect a wiring line at one side of the
core substrate to another wiring line at the opposed side,

wherein the insulation layer or layers have bores having a diameter larger than the
diameter of the holes so as to expose the land at a bottom of the bore, said land surrounding
the opening of the hole in which a lead pin of the electronic part is to be inserted such that
said bore communicates with the hole, and the lands connected to the wiring lines are
covered with the insulation layer.